

NEX94212-Q100

120 mA, 40 V low-dropout voltage regulator

Rev. 1 — 29 July 2025

Preliminary data sheet

1. General description

The NEX94212-Q100 device is a Low-Dropout (LDO) linear regulator with fixed output voltage of 5 V which can supply loads up to 120 mA. The device supports a wide input voltage range from 4 V to 40 V (up to 45 V transient) to withstand cold-cranking and load-dump transient conditions.

The device integrates multiple protection features. When configured as a power supply for off-board components (e.g., sensors) with external cables, the built-in short-to-battery and reverse polarity protections (-42 V) safeguard the system against harness failures. The device employs a back-to-back PMOS topology to block reverse current without requiring an external diode. The device also supports current limit protection to protect against output short-to-ground or overload conditions that will eventually trigger thermal shutdown if shorting or overloading lasts long.

The device switches to standby mode by pulling down the EN pin, which enables an ultra-low shutdown current of 0.65 μ A typical to extend battery life. It operates across an ambient temperature range from -40 °C to 125 °C, and a junction temperature range from -40 °C to 150 °C. Additionally, this device is available in SOT223 package.

Table 1. Device information

Part number	Package	Body size (nom)
NEX94212BDG-Q100	SOT223	6.5 mm x 3.5 mm

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - Ambient temperature (T_{amb}): -40 °C to 125 °C
 - Junction temperature (T_i): -40 °C to 150 °C
- Input voltage range: 4 V to 40 V
 - Absolute maximum input range: -42 V to 45 V
- Output voltage range: 5 V (fixed)
 - Absolute maximum output range: -1 V to 45 V
- Output voltage accuracy: ±1.5% (max)
- Maximum output current: 120 mA
- · Low dropout voltage:
 - 210 mV typical at 100 mA (V_{OUT} = 5 V)
- Low quiescent current (I_O):
 - 40 μA typical quiescent current at light loads
 - 0.65 μA typical shutdown current
- Active output discharge with a typical discharge current of 800 µA
- Stable with a wide range of ceramic output-stability cap:
 - ESR from 0.001 Ω to 5 Ω ; output capacitor from 4.7 μF to 470 μF
- Integrated fault protection features:
 - · Reverse polarity on input
 - Short to battery protection on output
 - · Reverse current protection
 - Short-circuit and overcurrent protection
 - Thermal shutdown
- Package: 4-pin SOT223
 - $R_{\theta JA} = 106.4 \, ^{\circ}\text{C/W}$

3. Applications

- Power supply for off-board sensors
- Powertrain of electric vehicles (EV) and hybrid electric vehicles (HEV)
- Body control modules (BCMs)
- · Automotive head units & clusters



4. Ordering information

Table 2. Ordering information

Type number	Temperature range (T _j)	Name	Description	Version
NEX94212BDG-Q100	-40 °C to 150 °C	SOT223	plastic surface-mounted package with increased heatsink; 4 leads	<u>SOT223</u>

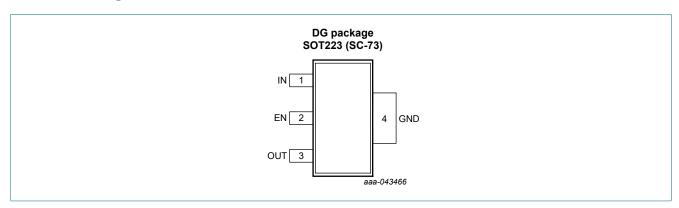
5. Marking

Table 3. Marking codes

Type number	Marking code
NEX94212BDG-Q100	N9212B

6. Pin configuration and description

6.1. Pin configuration



6.2. Pin description

Table 4. Pin description

Symbol	Pin	I/O	Description
IN	1	I	Input power-supply voltage pin. Place a small ceramic capacitor as close to the input of the device as possible to reduce line interference.
EN	2	Į	Enable logic pin, high level is enabled, low level is disabled.
OUT	3	0	Output voltage pin. Place a capacitor as close to the output of the device as possible, follow the capacitance and ESR requirements described in Table 8 .
GND	4	G	Ground pin. This pin is connected to ground internally.

7. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to ground (ground = 0 V).[1]

Symbol	Parameter	Min	Max	Unit
V _{IN}	input voltage	-42	45	V
V_{EN}	enable voltage	-42	45	V
V _{OUT}	output voltage	-1	45	V
T _{amb}	ambient temperature	-40	125	°C
Tj	junction temperature	-40	150	°C
T _{stg}	storage temperature	-65	165	°C

^[1] Stresses beyond those conditions under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

8. ESD ratings

Table 6. ESD ratings

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{ESD}	electrostatic	HBM: ANSI/ESDA/JEDEC JS-001 class 3A [1]	-4000	-	4000	V
VESD	discharge voltage	CDM: ANSI/ESDA/JEDEC JS-002 class C3 [2]	-1000	-	1000	V

^[1] HBM stress testing was performed in accordance with AEC-Q100-002.

9. Thermal information

Table 7. Thermal information

Thermal resistance according to JEDEC51-5 and -7.

Symbol	Parameter	SOT223 (SC-73)	Unit
$R_{\theta JA}$	junction to ambient thermal resistance	106.4	°C/W
$R_{\theta JC(top)}$	junction to case (top) thermal resistance	63.2	°C/W
$R_{\theta JB}$	junction to board thermal resistance	20.6	°C/W
Ψ_{JT}	junction to top char parameter	9.5	°C/W

^[2] CDM stress testing was performed in accordance with AEC-Q100-011.

10. Recommended operating conditions

Table 8. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{IN}	input voltage		4	-	40	V
I _{OUT}	output current	[1]	-	-	120	mA
V_{EN}	enable voltage		0	-	40	V
C _{IN}	input capacitance		-	1	-	μF
C _{OUT}	output capacitance	[2]	4.7	-	470	μF
ESR	output capacitor ESR requirements	[3]	0.001	-	5	Ω
T _{amb}	ambient temperature		-40	-	125	°C
Tj	junction temperature		-40	-	150	°C

- [1] Maximum output current when device is not thermal shutdown.
- [2] The minimum output capacitance requirement is applicable for a worst-case capacitance tolerance of 30%.
- [3] ESR shall be measured at 10 kHz. For capacitors with larger ESR, like ESR > 1 Ω, decouple with a 100 nF ceramic capacitor to improve transient response.

11. Electrical characteristics

Table 9. Electrical characteristics

At recommended operating conditions; T_j = -40 °C to 150 °C; V_{IN} = 13.5 V; C_{IN} = 1 μ F; C_{OUT} = 4.7 μ F; and V_{EN} = 2 V; (unless otherwise noted) voltages are referenced to GND (ground = 0 V).

Cumbal	Doromotor	Conditions	T _{amb} =	-40 °C to	125 °C	Unit
Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
Power sup	ply		'			
V _{IN}	input voltage range	fixed 5 V output, I _{OUT} = 1 mA	5.5	-	40	V
		V _{IN} rising	3.4	3.6	3.9	V
$V_{IN(UVLO)}$	under voltage lockout threshold	V _{IN} falling	3.0	3.2	3.4	V
	un conoid	hysteresis	-	400	-	mV
l _Q	quiescent current	V _{IN} = 5.5 V to 40 V; I _{OUT} = 100 μA	-	40	70	μΑ
I _{GND}	ground current	V _{IN} = 6 V to 40 V; I _{OUT} = 100 mA	-	-	1	mA
I _{SHUT}	shutdown current	V _{IN} = 4 V to 40 V; V _{EN} = 0 V	-	0.65	6	μΑ
I _{R(IN)}	reverse current at V _{IN}	V _{IN} = 0 V; V _{OUT} = 20 V; V _{EN} = 5 V	-1	-	0	μΑ
I _{R(-IN)}	reverse current at negative input voltage	V _{IN} = -20 V; V _{OUT} = 0 V; V _{EN} = 5 V	-5	-	0	μΑ
Enable inp	ut (EN)					
V _{EN_L}	logic input low level		-	-	0.7	V
V _{EN_H}	logic input high level		2	-	-	V
I _{EN}	EN pin current	V _{IN} = 13.5 V; V _{EN} = 5 V	-	-	5	μΑ
Output						_
V _{OUT}	output accuracy	V_{IN} = 6 V to 40 V (V_{OUT} = 5 V); I_{OUT} = 100 μ A to 120 mA	-1.5	-	1.5	%
$\Delta V_{OUT(\Delta V_{IN})}$	line regulation	V _{IN} = 6 V to 40 V; I _{OUT} = 10 mA	-	-	10	mV
$\Delta V_{OUT(\Delta I_{OUT})}$	load regulation	V _{IN} = 13.5 V; I _{OUT} = 100 μA to 120 mA	-	-	50	mV
V_{DO}	dropout voltage	V _{IN} = V _{OUT} = 5 V; I _{OUT} = 100 mA	-	210	380	mV
I _{OUT}	output current	V _{IN} = V _{OUT} + 1 V	-	-	120	mA

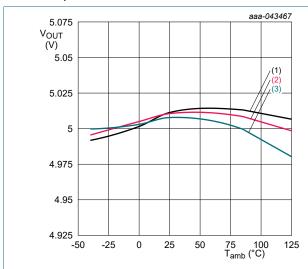
Cumbal	Parameter	Conditions	T _{amb} =	-40 °C to	125 °C	Unit
Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
I _{DIS}	discharge current	V _{IN} = 13.5 V; V _{OUT} = 5 V	-	800	-	μA
I _{CL}	output current limit	$V_{IN} = V_{OUT} + 1 V$; V_{OUT} short to 90% x V_{OUT}	120	160	200	mA
PSRR	power-supply ripple rejection	V_{IN} = 13.5 V; I_{OUT} = 10 mA; C_{OUT} = 4.7 μ F; frequency = 100 Hz [2]	-	80	-	dB
Operating	temperature range					
T _{SD}	junction thermal shutdown temperature	rising junction temperature [2]	-	175	-	°C
T _{HYST}	thermal shutdown hysteresis	[2]	-	20	-	°C

 ^[1] All typical values are measured at T_{amb} = 25 °C.
 [2] Guaranteed by design and bench test, not fully tested in production.

12. Typical characteristics

At recommended operating conditions, voltages are referenced to GND (ground = 0 V); typical values are at 25°C (unless otherwise noted).

 V_{IN} = 13.5 V, V_{EN} \geq 2 V, C_{IN} = 1 μ F, C_{OUT} = 4.7 μ F, V_{OUT} = 5 V, T_{amb} = -40 °C to 125 °C, T_j = -40 °C to 150 °C, unless otherwise specified.



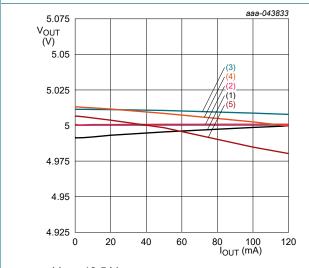
$$V_{OUT} = 5 V$$

(1)
$$I_{OUT} = 100 \mu A$$

(2)
$$I_{OUT} = 50 \text{ mA}$$

(3)
$$I_{OUT} = 120 \text{ mA}$$





$$V_{IN} = 13.5 V$$

(1)
$$T_{amb} = -40 \, ^{\circ}C$$

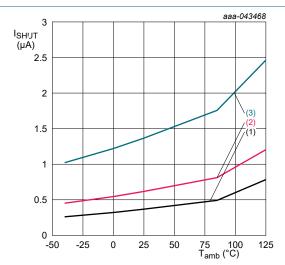
(2)
$$T_{amb} = 0$$
 °C

(3)
$$T_{amb} = 25 \, ^{\circ}C$$

(4)
$$T_{amb}$$
 = 85 °C

(5)
$$T_{amb} = 125 \, ^{\circ}C$$

Fig. 3. Load regulation

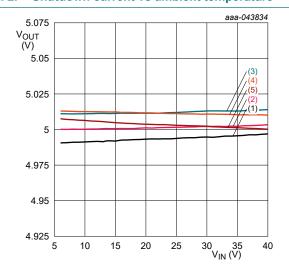


(1)
$$V_{IN} = 4 V$$

(2)
$$V_{IN} = 13.5 \text{ V}$$

(3)
$$V_{IN} = 40 \text{ V}$$

Fig. 2. Shutdown current vs ambient temperature



$$I_{OUT} = 10 \text{ mA}$$

(1)
$$T_{amb} = -40 \, ^{\circ}C$$

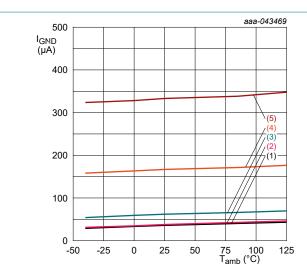
(2)
$$T_{amb} = 0$$
 °C

(3)
$$T_{amb} = 25 \, ^{\circ}C$$

(4)
$$T_{amb} = 85 \, ^{\circ}C$$

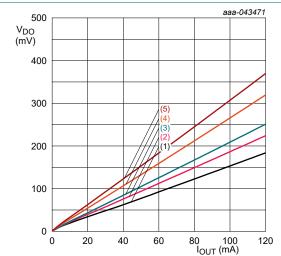
(5)
$$T_{amb} = 125 \, ^{\circ}C$$

Fig. 4. Line regulation



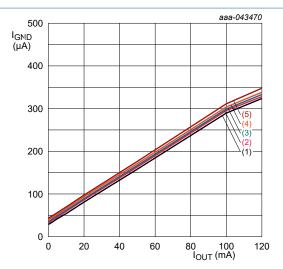
- (1) $I_{OUT} = 100 \mu A$
- (2) $I_{OUT} = 1 \text{ mA}$
- (3) $I_{OUT} = 10 \text{ mA}$
- (4) $I_{OUT} = 50 \text{ mA}$
- (5) $I_{OUT} = 120 \text{ mA}$

Fig. 5. Ground current vs ambient temperature



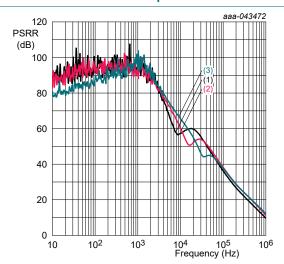
- (1) $T_{amb} = -40 \, ^{\circ}C$
- (2) T_{amb} = 0 °C
- (3) $T_{amb} = 25 \, ^{\circ}C$
- (4) $T_{amb} = 85 \, ^{\circ}C$
- (5) T_{amb} = 125 °C

Fig. 7. Dropout voltage vs output current



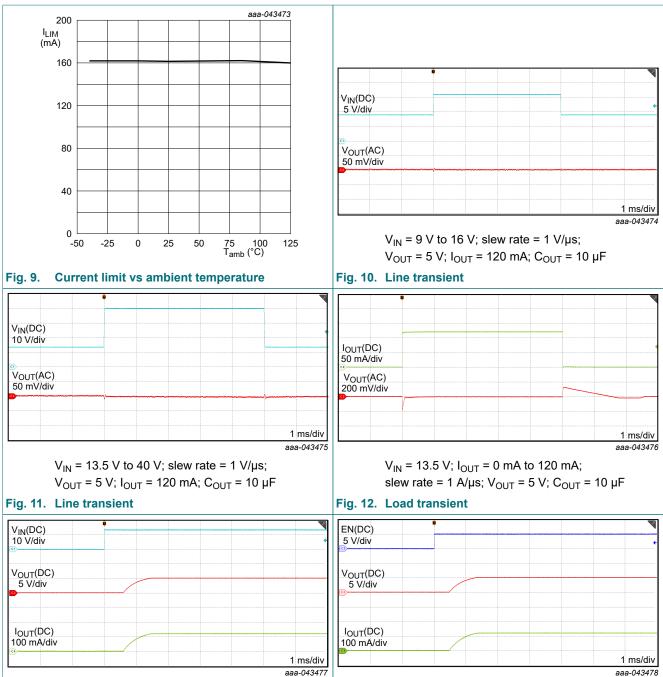
- (1) $T_{amb} = -40 \, ^{\circ}C$
- (2) $T_{amb} = 0$ °C
- (3) $T_{amb} = 25 \, ^{\circ}C$
- (4) T_{amb} = 85 °C
- (5) $T_{amb} = 125 \, ^{\circ}C$

Fig. 6. Ground current vs output current



- V_{IN} = 13.5 V; C_{OUT} = 4.7 μF
- (1) $I_{OUT} = 1 \text{ mA}$
- (2) $I_{OUT} = 10 \text{ mA}$
- (3) $I_{OUT} = 100 \text{ mA}$

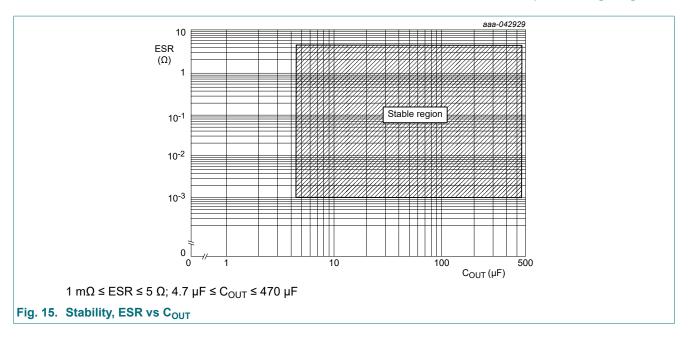
Fig. 8. PSRR vs frequency



 V_{EN} = 5 V; V_{IN} from 0 V to 13.5 V;

 $V_{OUT} = 5 \text{ V}; I_{OUT} = 120 \text{ mA}; C_{OUT} = 10 \mu\text{F}$

Fig. 14. Start up by EN



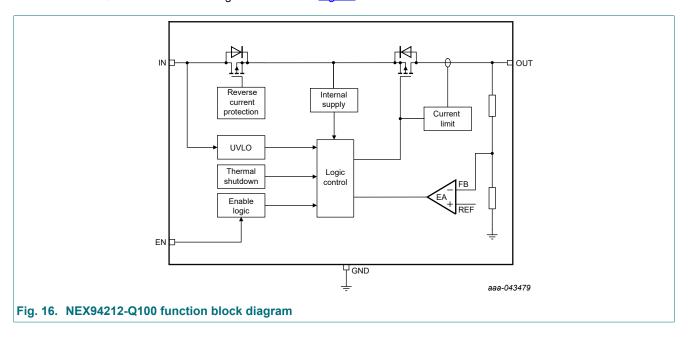
13. Detailed description

13.1. Overview

The NEX94212-Q100 is a Low-Dropout (LDO) linear regulator designed to connect to batteries in automotive applications. The device has an input voltage range extending to 40 V (45 V max), which allows the device to withstand transients (such as load dump) that are anticipated in automotive systems. The device has only a 40 μ A typical quiescent current at light load and 0.65 μ A typical shutdown current under disabled mode. The device offers multiple protection features, including reverse polarity protection and safeguarding against shorting to the battery and ground.

13.2. Function block diagram

The NEX94212-Q100 function block diagram is shown in Fig. 16.



13.3. Feature description

13.3.1. Device enable (EN)

The enable pin is a high-voltage-tolerant pin. A high input on EN activates the device and turns on the regulator. Connect this pin to an external Microcontroller Unit (MCU) or a digital circuit to enable and disable the device or connect it to the IN pin for self-bias applications.

13.3.2. Undervoltage lockout (UVLO)

An undervoltage lockout (UVLO) circuit is to stop the operation of the device when the input voltage drops below the typical falling threshold $V_{IN\,(UVLO)}$. To prevent the device from turning off when the input drops during turn-on, check the hysteresis values of UVLO specified in the <u>Electrical Characteristics table</u> beforehand. If the input voltage has a negative transient that drops below the UVLO threshold and recovers, the regulator shuts down and powers up with a normal power-up sequence when the input voltage is above the required level.

13.3.3. Current limit operation

The device has an internal current limit circuit that protects the regulator during transient high-load current faults or shorting events.

When a current limit event occurs, the device begins to heat up because of the increase in power dissipation. When the device achieves the current limit I_{CL} , the pass transistor dissipates power $[(V_{IN} - V_{OUT}) \times I_{CL}]$.

If a thermal shutdown is triggered, the device turns off. After the device cools down, the internal thermal shutdown circuit turns the device back on. If the output current fault continues, the device cycles between the current limit and thermal shutdown.

13.3.4. Thermal protection

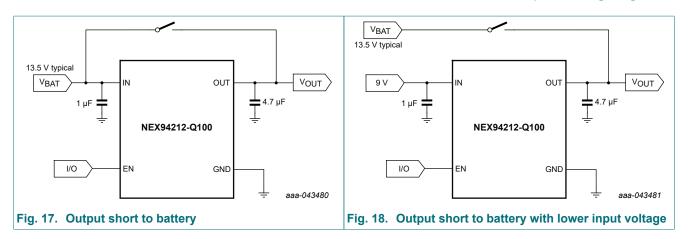
The NEX94212-Q100 is integrated with an internal temperature sensor to monitor internal junction temperature (T_j) . If T_j exceeds the thermal shutdown temperature T_{SD} at 175 °C, the device stops working. When T_j drops below the hysteresis level of typical 20 °C, the device starts operating again.

Thermal shutdown might be triggered during start-up due to large inrush current charging large output capacitance, or high $(V_{IN} - V_{OUT})$ regulations under heavy loads due to large power dissipation across the die. Proper heat sinking needs to be considered under these high power dissipation conditions.

13.3.5. Output short to battery and reverse protection

The NEX94212-Q100 employs a back-to-back PMOS topology to protect the device from damage during fault conditions where V_{OUT} exceeds V_{IN} , effectively blocking reverse current flow. The device remains undamaged as long as it operates within the range described in Limiting values. This integrated protection eliminates the requirement for an external diode.

The NEX94212-Q100 survives, and no damage occurs to the device when the output is shorted to the battery as shown in Fig. 17. And a shorting to battery might also occur when the device is powered by a lower separated input voltage supply as shown in Fig. 18. In this case, the NEX94212-Q100 input supply is set at 9 V when a shorting to battery (13.5 V typical) occurs on output, which typically runs at 5 V. The continuous reverse current that flows out through the input pin is less than $5 \mu A$.



13.3.6. Active output discharge

The device incorporates an active output discharge function when enabled, ensuring that the output voltage rapidly returns to its nominal level during overvoltage fluctuations. This is particularly effective during load transients such as heavy-to-light load transitions.

When the output voltage exceeds the nominal level, the device activates a FET that connects a resistor with the resistance value of several thousands of ohms and the ground to achieve active discharge. Under these conditions, the output sources a typical current of 800 μ A (at output voltage of 5 V) through this resistance network, even without an external load.

13.4. Device functional modes

13.4.1. Device functional mode comparison

<u>Table 10</u> shows the conditions that lead to the different modes of operation. See the <u>Table 9</u> table for recommended operating conditions.

Table 10. Device functional mode comparison

Operating mode	V _{IN}	V _{EN}	I _{OUT}	Tj
Normal operation	$V_{IN} \ge V_{OUT(nom)} + V_{DO}$ and $V_{IN} \ge V_{IN(min)}$ [1]	V _{EN} > V _{EN_H}	$I_{OUT} \le I_{OUT(max)}$	$T_j < T_{SD}$
Dropout operation	$V_{IN(min)} \le V_{IN} < V_{OUT(nom)} + V_{DO}$	$V_{EN} > V_{EN_H}$	$I_{OUT} \le I_{OUT(max)}$	$T_j < T_{SD}$
Disabled mode	V _{IN} < V _{UVLO}	V _{EN} < V _{EN_L}	Not applicable	$T_j > T_{SD}$

[1] $V_{OUT(nom)}$ is nominal output voltage; $V_{IN(min)}$ is minim input voltage.

13.4.2. Normal operation

The device works at nominal voltage when all the following conditions are met:

- · The output current is less than the current limit.
- · The device's junction temperature is less than thermal shutdown temperature.
- The enable pin voltage has previously exceeded the enable rising threshold voltage and has not yet decreased to less than the enable falling threshold.

13.4.3. Dropout operation

The device operates in dropout mode when the input voltage is less than the sum of target output voltage plus the dropout voltage and all other conditions are met for normal operation.

In this mode, the output voltage tracks the input voltage. The transient performance of the device becomes significantly degraded because the pass element is in the ohmic or triode region and acts as a switch. Line or load transients in dropout can result in large output-voltage deviations.

NEX94212_Q100

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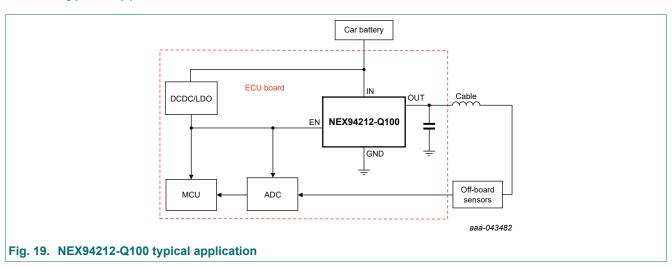
When the input voltage returns to a value greater than or equal to the sum of nominal output voltage plus the dropout voltage $[V_{OUT(NOM)} + V_{DO}]$, the output voltage can overshoot for a short period of time while the device pulls the pass element back into the linear region.

13.5. Application implementation

13.5.1. Application information

The following section is a reference to simplify the system design with the NEX94212-Q100 typical application for external components calculation and selection.

13.5.2. Typical application



13.5.2.1. Design requirements

A typical application is applied to automotives and power supply for off-board sensors, which normally requires 5 V output. The design parameters are listed in Table 11.

Table 11. Design parameters

Parameters	Values
Input voltage	6 V to 40 V
Output voltage	5 V
Output current	120 mA max
Input capacitance	10 μF
Output capacitance	10 μF

13.5.2.2. Detailed design procedure

13.5.2.2.1. Input capacitor

The device requires an input decoupling capacitor, the value of which depends on the application. The typical recommended value for the decoupling capacitor is 1 µF. The voltage rating must be greater than the maximum input voltage.

13.5.2.2.2. Output capacitor

To ensure the stability of the NEX94212-Q100, the device requires an output capacitor with a value of 4.7 μ F to 470 μ F from OUT to GND and the ESR range between 0.001 Ω and 5 Ω . It is recommended to select a ceramic capacitor with low ESR to improve the load transient response and ripple performance.

14. Layout

14.1. Layout guidelines

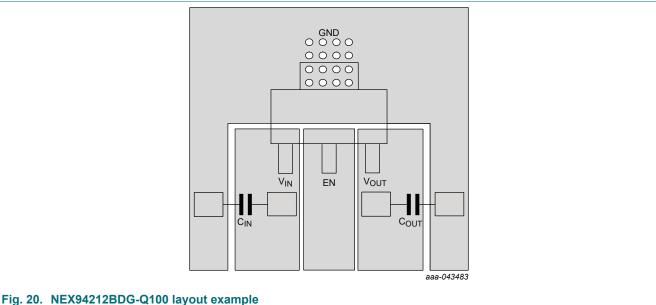
For best overall performance, the following guidelines are recommended for the LDO layout:

- Place all circuit components on the same side of the circuit board and as near as practical to the respective LDO pin connections.
- Place ground return connections to the input and output capacitor, and to the LDO ground pin as close as possible to each other, connected by a wide, component-side, copper surface.
- The use of vias and long traces to the input and output capacitors is strongly discouraged and negatively affects system performance.
- In most applications, the ground plane is necessary to meet thermal requirements.

A ground reference plane should either be embedded in the PCB itself or located on the bottom side of the PCB opposite the components. This reference plane serves to assure accuracy of the output voltage, shield noise, and behaves similarly to a thermal plane to spread (or sink) the heat from the LDO device when connected to the thermal pad.

14.2. Layout examples

Fig. 20 shows a layout example of NEX94212BDG-Q100 (SOT223) device.



15. Package outline

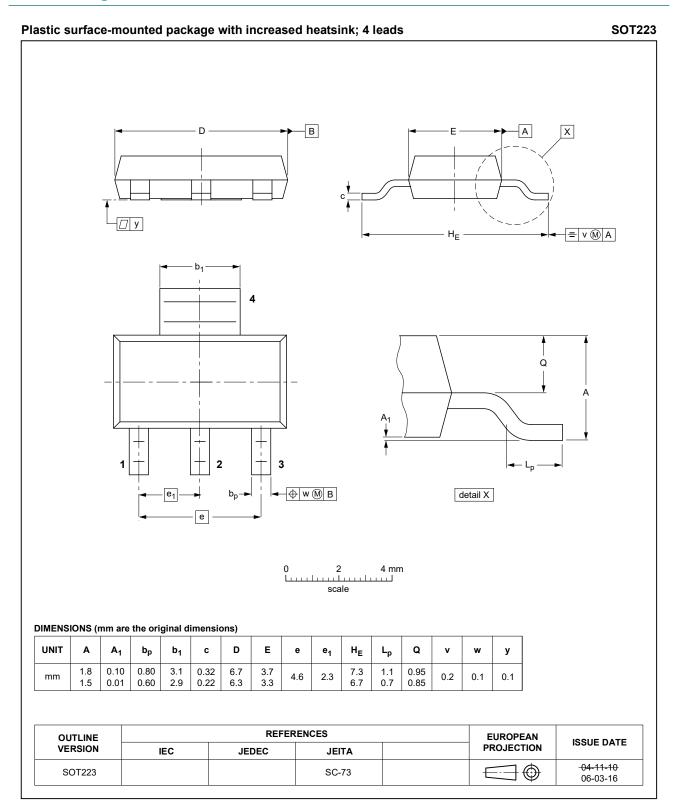


Fig. 21. Package outline SOT223 (SC-73)

16. Abbreviations

Table 12. Abbreviations

Acronym	Description			
AEC	Automotive Electronics Council			
ANSI	American National Standards Institute			
ВСМ	Body Control Module			
CDM	Charge Device Model			
ESD	Electrostatic Discharge			
ESDA	ElectroStatic Discharge Association			
EV	Electric Vehicle			
НВМ	Human Body Model			
HEV	Hybrid Electric Vehicle			
JEDEC	Joint Electron Device Engineering Council			
LDO	Low-Dropout			
MCU	Microcontroller Unit			
PSRR	Power Supply Ripple Rejection			
UVLO	Undervoltage Lockout			

17. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
NEX94212_Q100 v. 1	20250729	Preliminary data sheet	-	-

18. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at https://www.nexperia.com.

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